Global Communication Semiconductors, LLC
Corporate & Foundry
23155 Kashiwa Court, Torrance, CA 90505
Telephone: 310-530-7274 Fax: 310-517-8200
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Manufacturing Process Engineer – Grind and Polish

Job Req.	#0714
Department:	Manufacturing Engineering
Status:	Full-Time / Salaried
Shift:	8:00 am – 5:00 pm

Job Description

Supports pre-production, develops new processes, installs new processes, qualifies new processes, implements improvements into production flow, and handles details of ramping up of chosen products. The candidate

- Mainly responsible for wafer grind and polish
- Develops new processes and monitors process related SPC, tool performance
- Runs DOE for new process development or process improvements as needed
- Trains operators/technicians and maintains process documentations

Job Requirements

- B.S. in Science or Engineering
- 3-5 years' experience in semicoductor FAB related to wafer grind and polish
- Must have a good understanding of III-V compound semiconductor device and the overall process technologies, and have a grasp of the wafer process flow from beginning of the front side process to the backside.
- Intermediate skills in MS Office tools (Excel, PowerPoint, Outlook)